200V 8.0mΩ N-Ch Power MOSFET

Features

- Ultra-low ON-resistance, $R_{DS(ON)}$
- Low Gate Charge, Q_g
- 100% UIS and R_g Tested
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant

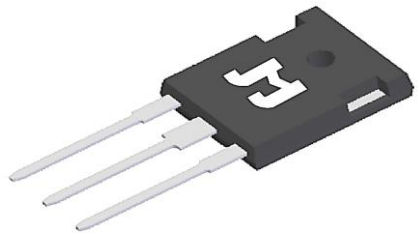
Product Summary

Parameter	Value	Unit
V_{DS}	200	V
$V_{GS(th)\_Typ}$	3.0	V
I_D (@ V_{GS} = 10V) (1)	122	A
$R_{DS(ON)\_Typ}$ (@ V_{GS} = 10V)	8.0	mΩ

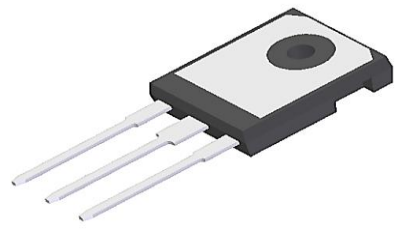
Applications

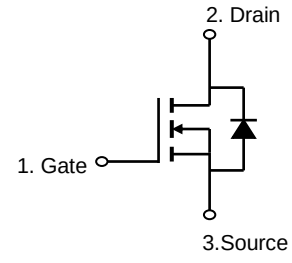
- Power Management in Computing, CE, IE 4.0, Communications
- Current Switching in DC/DC & AC/DC (SR) Sub-systems
- Load Switching, Quick/Wireless Charging, Motor Driving

TO-247-3L Top View



TO-247-3L Bottom View





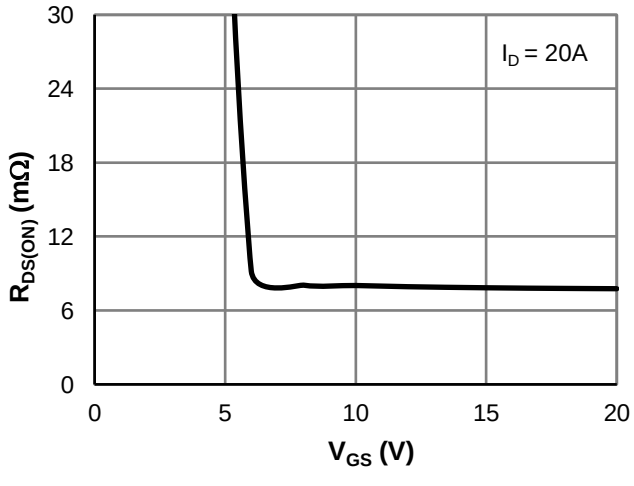
Ordering Information

Device	Package	# of Pins	Marking	MSL	T_J (°C)	Media	Quantity (pcs)
JMSH2010PS-U	TO-247-3L	3	SH2010P	NA	-55 to 150	Tube	30

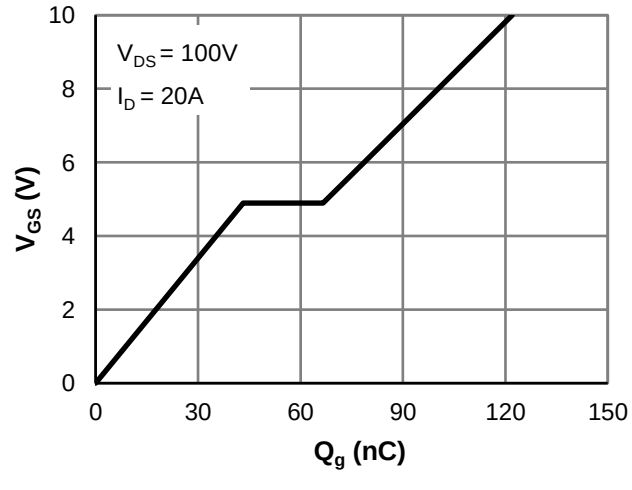
Absolute Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V_{DS}	200	V
Gate-to-Source Voltage		V_{GS}	±20	V
Continuous Drain Current (1)	T_C = 25°C	I_D	122	A
	T_C = 100°C		77	
Pulsed Drain Current (2)		I_{DM}	233	A
Avalanche Energy (3)		E_{AS}	1094	mJ
Power Dissipation (4)	T_C = 25°C	P_D	367	W
	T_C = 100°C		147	
Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

$R_{DS(ON)}$ vs. V_{GS}



Gate Charge



Electrical Characteristics (@ T_J = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	I_D = 250μA, V_{GS} = 0V	200			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 160V, V_{GS} = 0V			1.0	μA
		T_J = 55°C			5.0	
Gate-Body Leakage Current	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	2.0	3.0	4.0	V
Static Drain-Source ON-Resistance	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 20A		8.0	9.6	mΩ
Forward Transconductance	g_{FS}	V_{DS} = 5V, I_D = 20A		57		S
Diode Forward Voltage	V_{SD}	I_S = 1A, V_{GS} = 0V		0.70	1.0	V
Diode Continuous Current	I_S	T_C = 25°C			122	A
DYNAMIC PARAMETERS (5)						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 100V, f = 1MHz		8788		pF
Output Capacitance	C_{oss}			455		pF
Reverse Transfer Capacitance	C_{rss}			17.1		pF
Gate Resistance	R_g	V_{GS} = 0V, V_{DS}= 0V, f = 1MHz		4.7		Ω
SWITCHING PARAMETERS (5)						
Total Gate Charge (@ V_{GS} = 10V)	Q_g	V_{GS} = 0 to 10V V_{DS} = 100V, I_D = 20A		122		nC
Total Gate Charge (@ V_{GS} = 6V)	Q_g			79		nC
Gate Source Charge	Q_{gs}			43		nC
Gate Drain Charge	Q_{gd}			23		nC
Turn-On DelayTime	$t_{D(on)}$	V_{GS} = 10V, V_{DS} = 100V R_L = 5Ω, R_{GEN} = 3Ω		30		ns
Turn-On Rise Time	t_r			58		ns
Turn-Off DelayTime	$t_{D(off)}$			98		ns
Turn-Off Fall Time	t_f			43		ns
Body Diode Reverse Recovery Time	t_{rr}	I_F = 20A, dI_F/dt = 100A/μs		186		ns
Body Diode Reverse Recovery Charge	Q_{rr}	I_F = 20A, dI_F/dt = 100A/μs		743		nC

Thermal Performance

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	$R_{θJA}$	49	59	°C/W
Thermal Resistance, Junction-to-Case	$R_{θJC}$	0.34	0.41	°C/W

Notes:

1. Computed continuous current assumes the condition of T_{J_Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under T_{J_Max} = 150°C.
3. E_{AS} of 1094 mJ is based on starting T_J = 25°C, L = 3.0mH, I_{AS} = 27A, V_{GS} = 10V, V_{DD} = 100V; 100% test at L = 0.3mH, I_{AS} = 56A.
4. The power dissipation P_D is based on T_{J_Max} = 150°C.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical & Thermal Characteristics

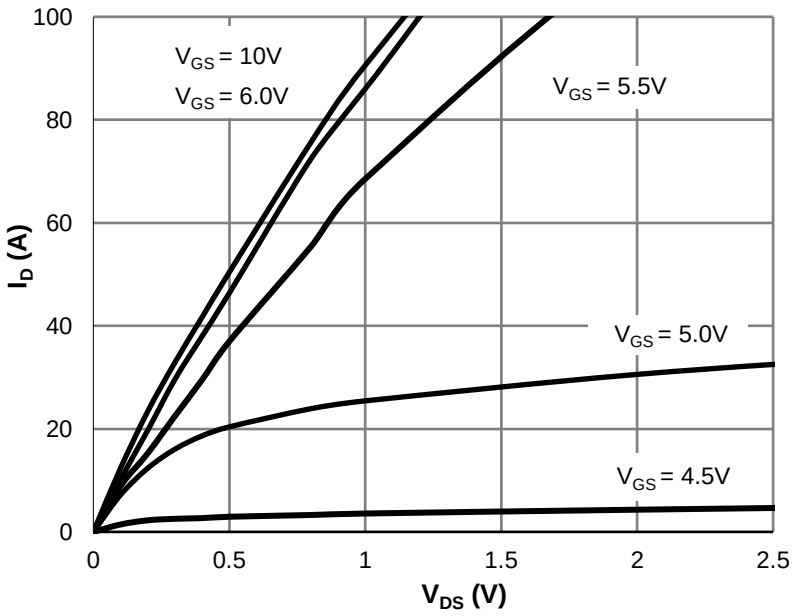


Figure 1: Saturation Characteristics

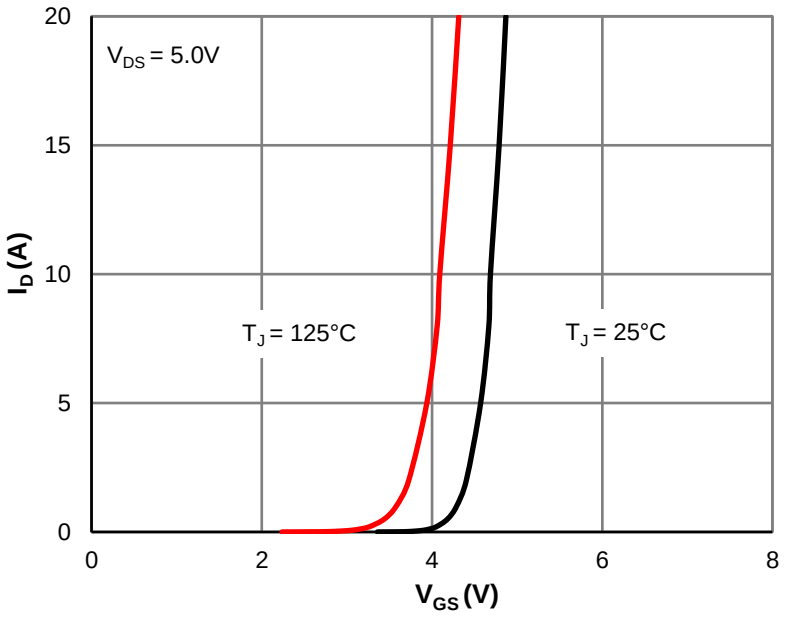


Figure 2: Transfer Characteristics

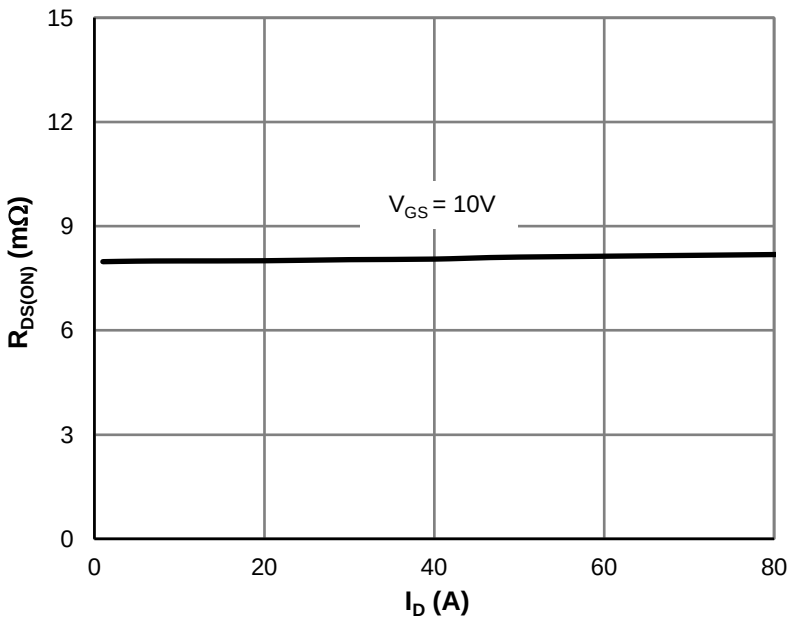


Figure 3: $R_{DS(ON)}$ vs. Drain Current

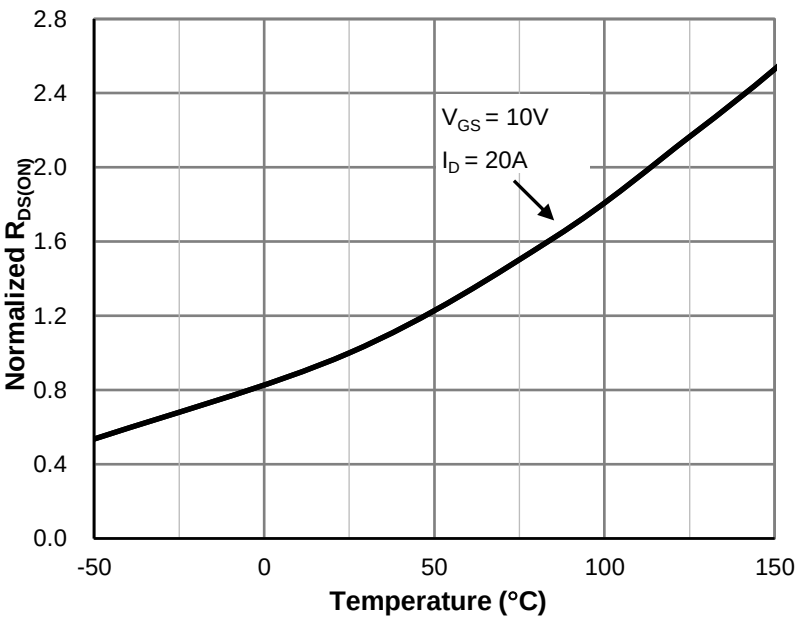


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

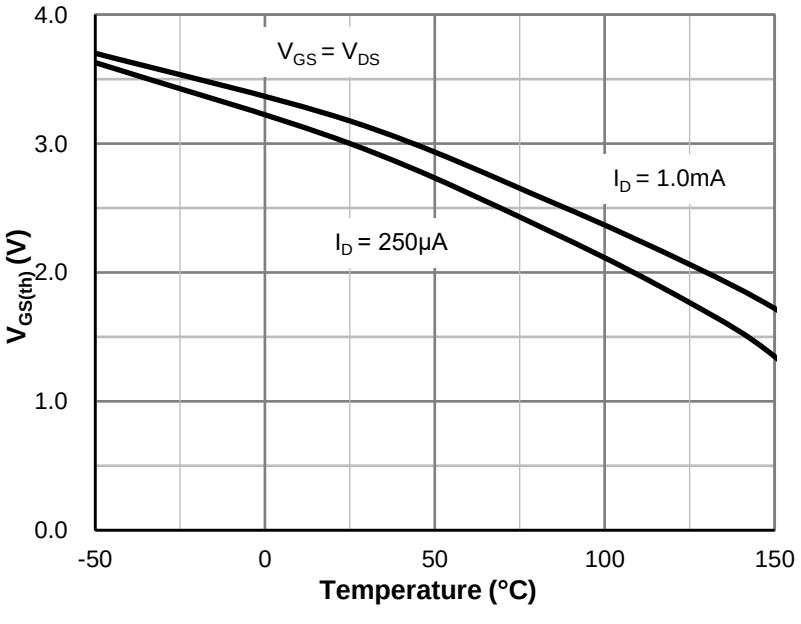


Figure 5: $V_{GS(th)}$ vs. Junction Temperature

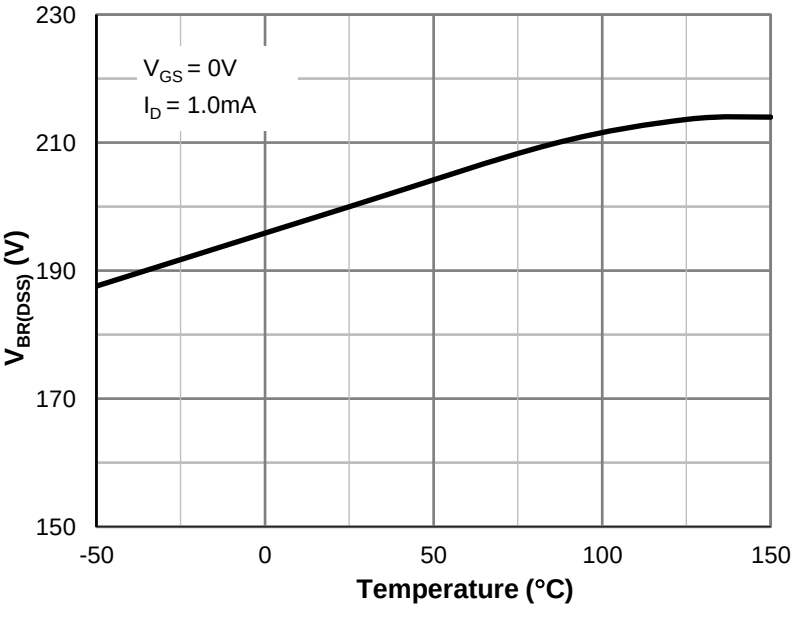


Figure 6: $V_{BR(DSS)}$ vs. Junction Temperature

Typical Electrical & Thermal Characteristics

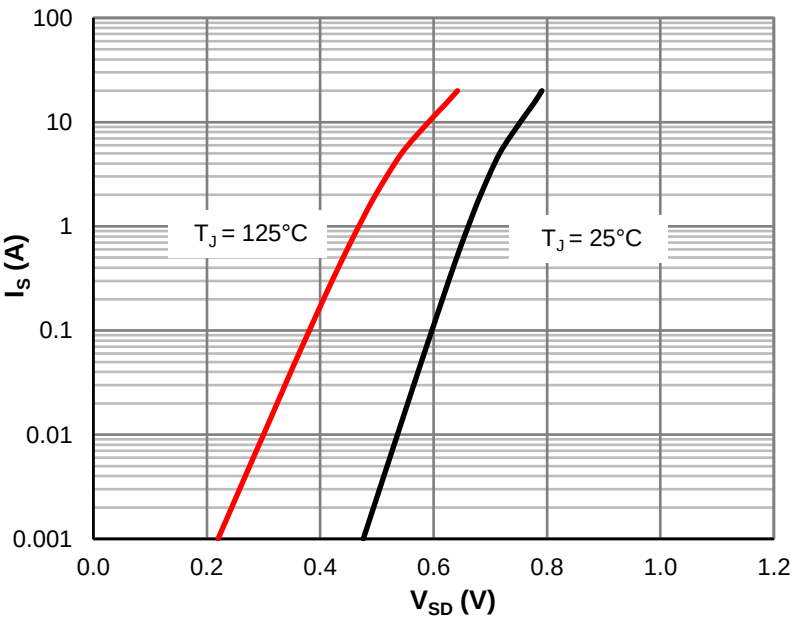


Figure 7: Body-Diode Characteristics

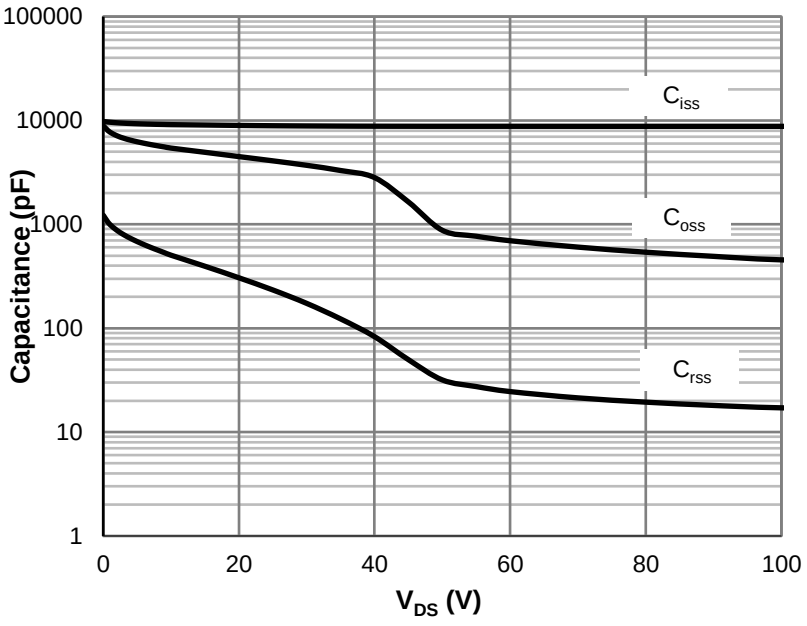


Figure 8: Capacitance Characteristics

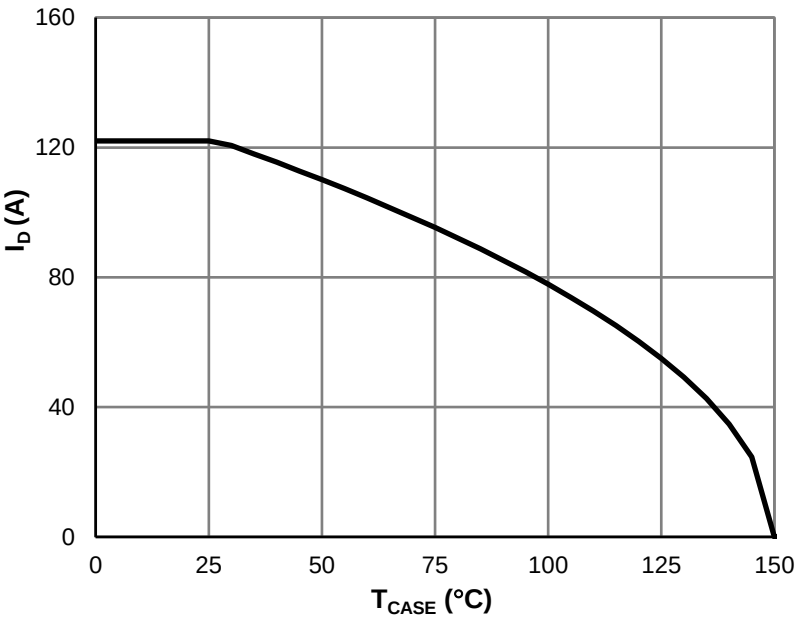


Figure 9: Current De-rating

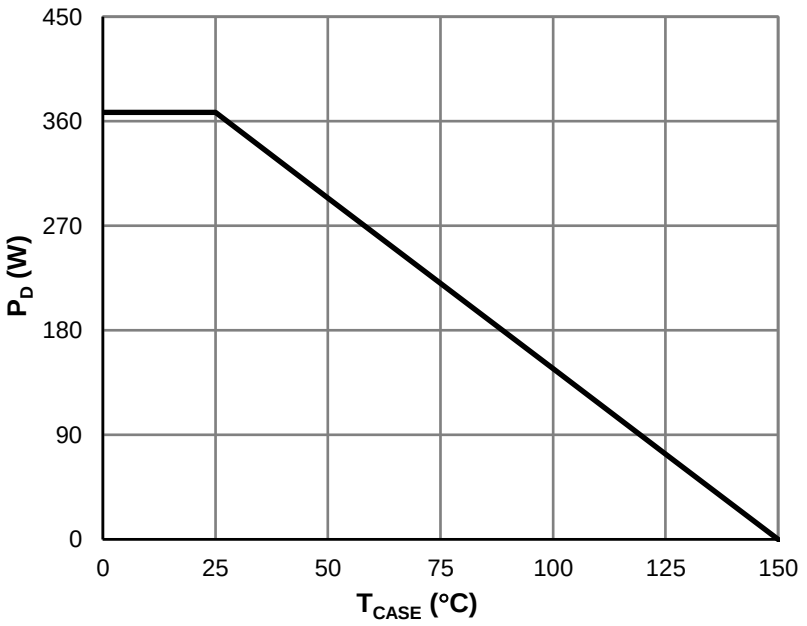


Figure 10: Power De-rating

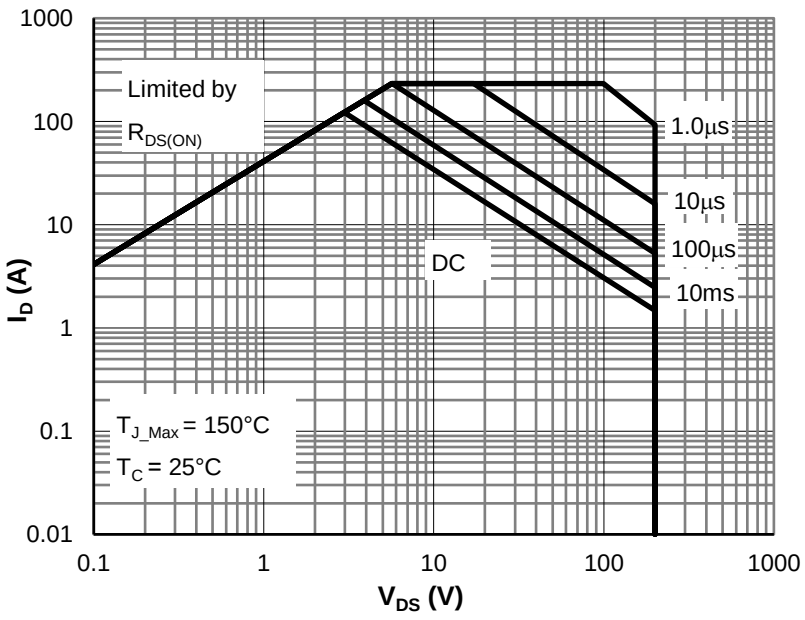


Figure 11: Maximum Safe Operating Area

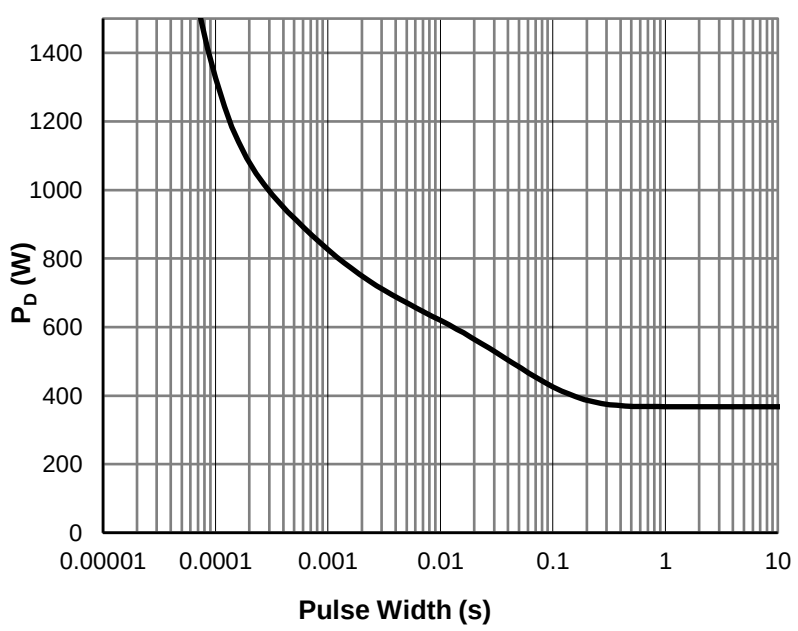


Figure 12: Single Pulse Power Rating, Junction-to-Case

Typical Electrical & Thermal Characteristics

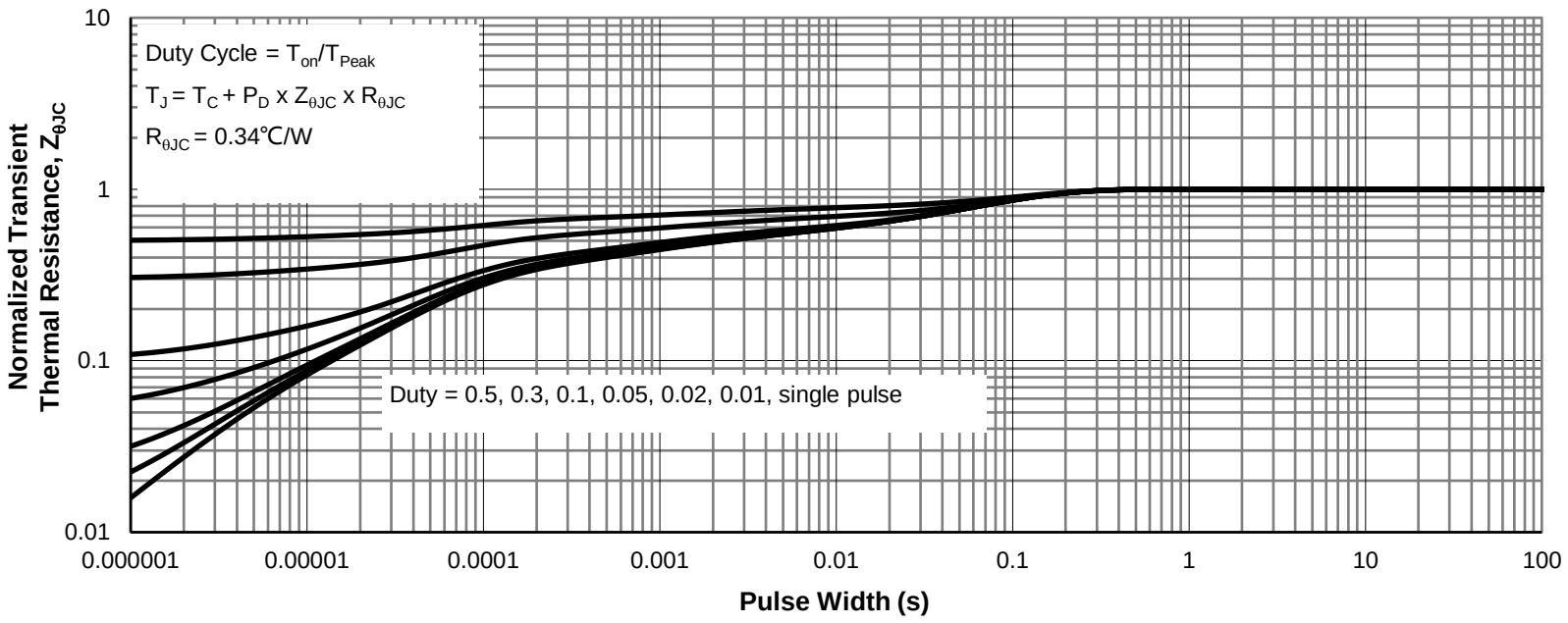
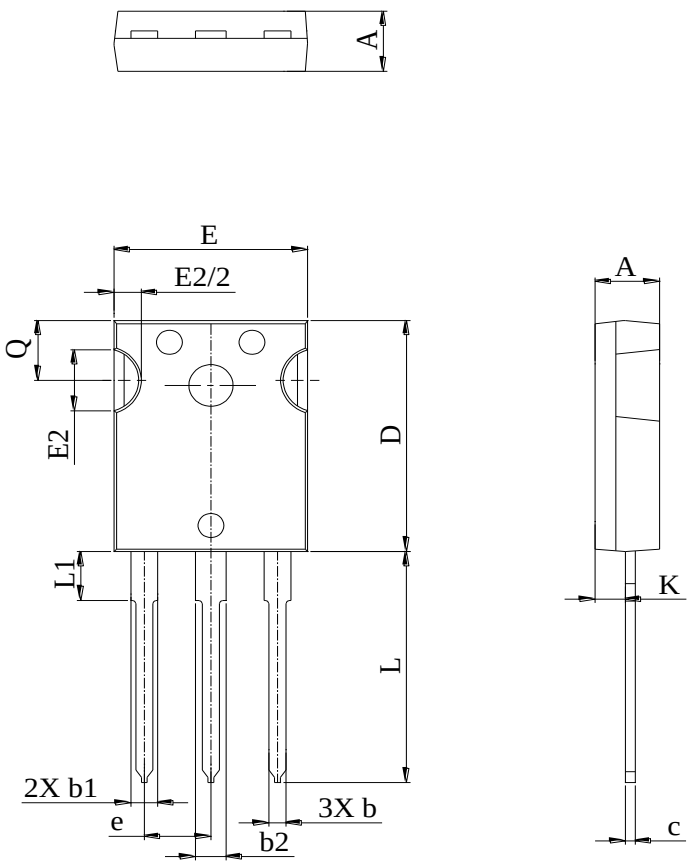


Figure 13: Normalized Maximum Transient Thermal Impedance

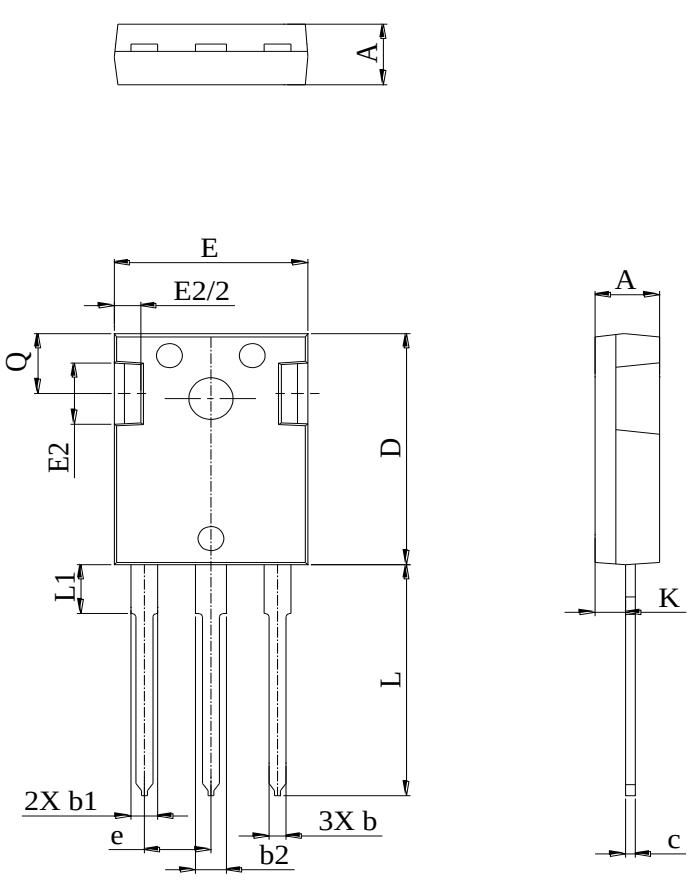
TO-247-3L Package Information

Type_A Package Outline



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.80	5.02	5.21
b	1.00	1.20	1.40
b1	1.90	2.00	2.39
b2	2.87	3.00	3.22
c	0.41	0.60	0.79
D	20.80	21.00	21.20
E	15.50	15.94	16.13
E2	4.32		5.49
L	19.70	20.07	20.32
L1	4.00		4.40
K	2.20		2.50
e	5.44 BSC		

Type_B Package Outline



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.80	5.02	5.21
b	1.00	1.20	1.40
b1	1.90	2.00	2.39
b2	2.87	3.00	3.22
c	0.41	0.60	0.79
D	20.80	21.00	21.20
E	15.50	15.94	16.13
E2	4.32		5.49
L	19.70	20.07	20.32
L1	4.00		4.40
K	2.20		2.50
e	5.44 BSC		